L Number	Hits	Search Text	DB	Time stamp
-	0	(printed adj wiring adj board) and (carrier adj substrate) and (vapor with copper) and (electrodeposited with copper)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/07/28 06:45
-	109	(printed adj wiring adj board) and (carrier adj substrate)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/07/28 06:45
-	71	((printed adj wiring adj board) and (carrier adj substrate)) and copper	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/07/28 06:45
-	56	(((printed adj wiring adj board) and (carrier adj substrate)) and copper) and separat$4	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/07/28 06:46
-	24	((((printed adj wiring adj board) and (carrier adj substrate)) and copper) and separat$4) and oxide	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/07/28 06:46
-	20	(((((printed adj wiring adj board) and (carrier adj substrate)) and copper) and separat$4) and oxide) and (separat$4 with substrate)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/07/28 06:53
-	1309	((wiring adj board) and (separat$4 with (substrate or carrier)))	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/07/28 06:53
-	203	((wiring adj board) and (separat$4 with (substrate or carrier))).ab.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/07/28 06:54
-	32	(((wiring adj board) and (separat$4 with (substrate or carrier))).ab.) and copper	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/07/28 07:04
-	9	("3281339" | "3616186" | "3936548" | "3984598" | "3998601" | "4293617" | "4357395" | "4394419" | "5863410").PN.	USPAT	2003/07/28 06:56
-	5	((((wiring adj board) and (separat$4 with (substrate or carrier))).ab.) and copper) and (vapor or cvd)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/07/28 07:10
-	3	((copper adj foil) and (vapor or cvd or deposition) and (separat$4 with (substrate or carrier))).ab.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/07/28 07:12
-	232	((copper adj foil) and (vapor or cvd or deposition)).ab.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/07/28 07:13
-	10	(((copper adj foil) and (vapor or cvd or deposition)).ab.) and (electroplat$4 with copper)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/07/28 07:18
-	586	((vapor or cvd) with copper) with ((electroplat$4 or electrodepos$5) with copper)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/07/28 07:20
-	0	(((vapor or cvd) with copper) with ((electroplat$4 or electrodepos$5) with copper).ab.) and coppper and foil	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/07/28 07:20
-	61	((vapor or cvd) with copper) with ((electroplat$4 or electrodepos$5) with copper).ab.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/07/28 07:20

		63	257/251.ccls.		USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/07/28 07:41